mail

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

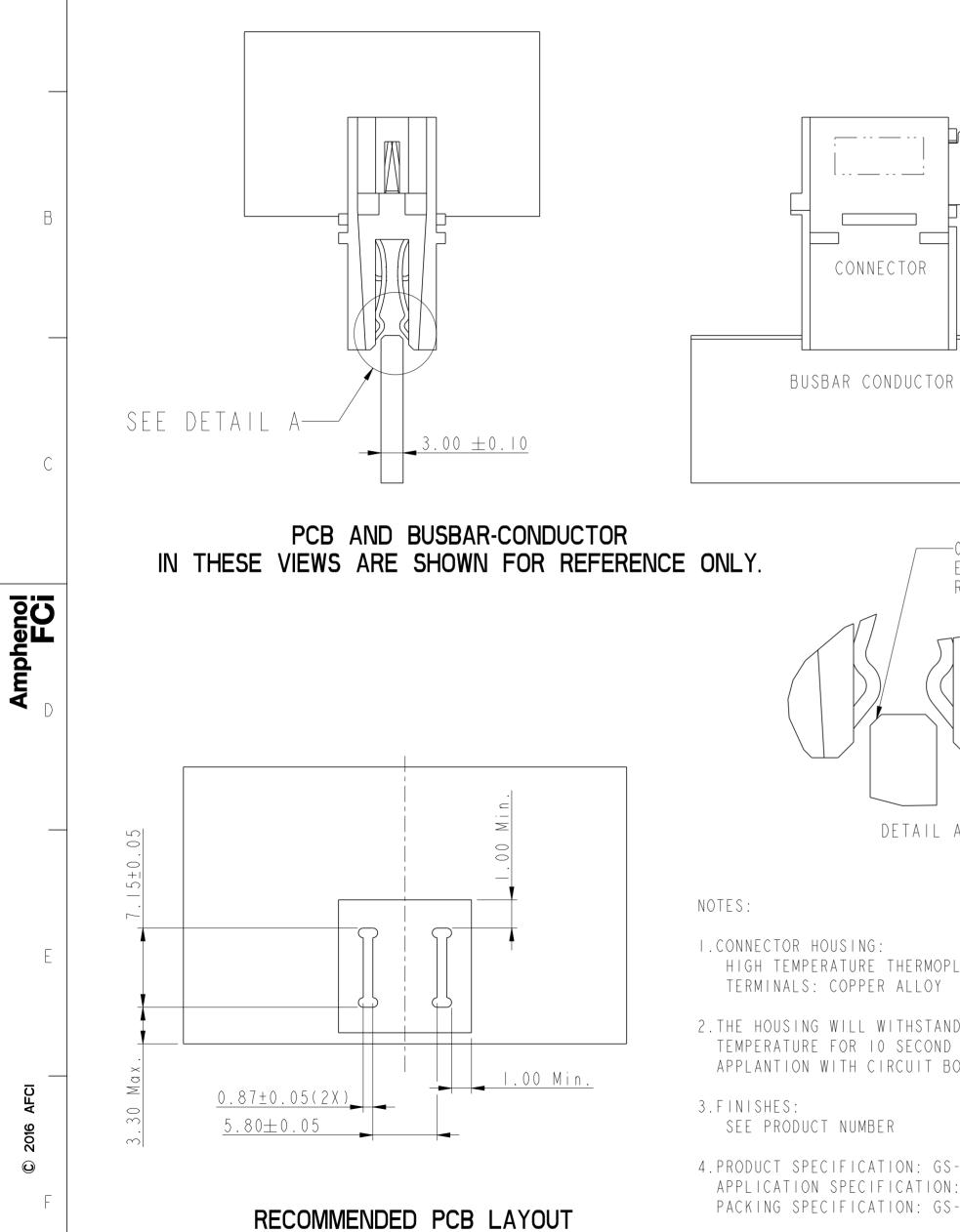


Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



			2	3		4	
	PRODUCT NUMBER	DESCRIPT	ION(PLATING)		Dim. A	Dim. B	PCB THICKNESS
	10125600-S01LF	CONTACT AF	REA:AGT PLATING-3.0um SILVER O	VER 1.27um NICKEL /	5.68	2.70	4.80 Max.
	10125600-S02LF	CONTACT AF	REA:AGT PLATING-3.0um SILVER O	4.00	2.00 Max.		
٨	10125600-S02LF	CONTACT AF	REA:AGT PLATING-3.0um SILVER O	VER I.27um NICKEL 应	4.40	4.00	



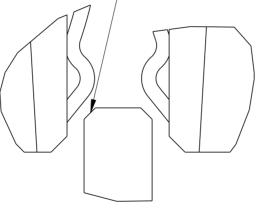
THICKNESS 4.8mm Max.

AFCI

2016

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-0.5mm Min.RADIUSED OR CHAMFERED EDGE ON BUSBAR CONDUCTOR RECOMMENDED



DETAIL A (6:1)

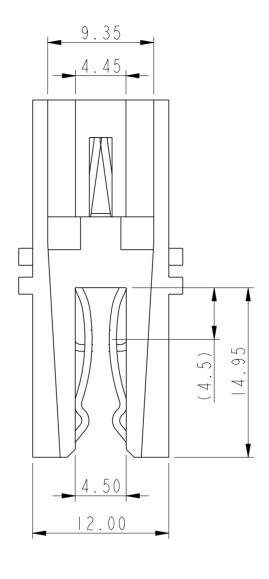
- HIGH TEMPERATURE THERMOPLASTIC GLASS FILLED, UL 94V-0 TERMINALS: COPPER ALLOY
- 2. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECOND IN A WAVE SOLDER APPLANTION WITH CIRCUIT BOARD.

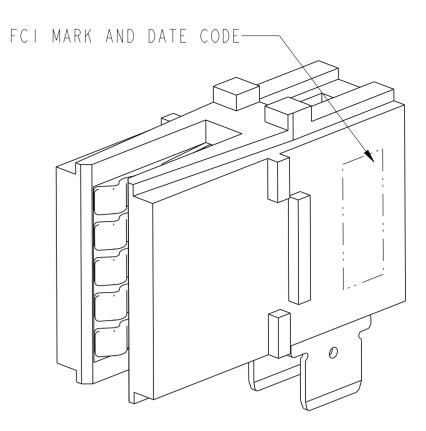
SEE PRODUCT NUMBER

- 4. PRODUCT SPECIFICATION: GS-12-1179 APPLICATION SPECIFICATION: GS-20-0396 PACKING SPECIFICATION: GS-14-2376
- 5. THE CONNECTOR MUST BE SUPPORTED WITH A FIXTURE DURING WAVE SOLDERING PROCESS

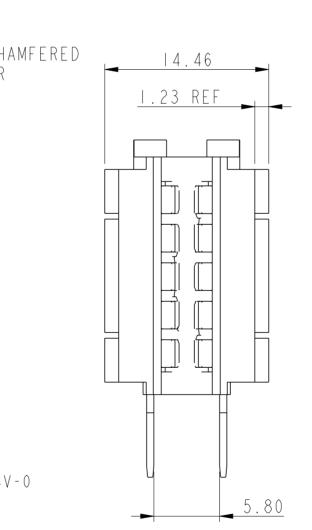
Creo File - REV E - 2016-02-12					
		2	3	4	

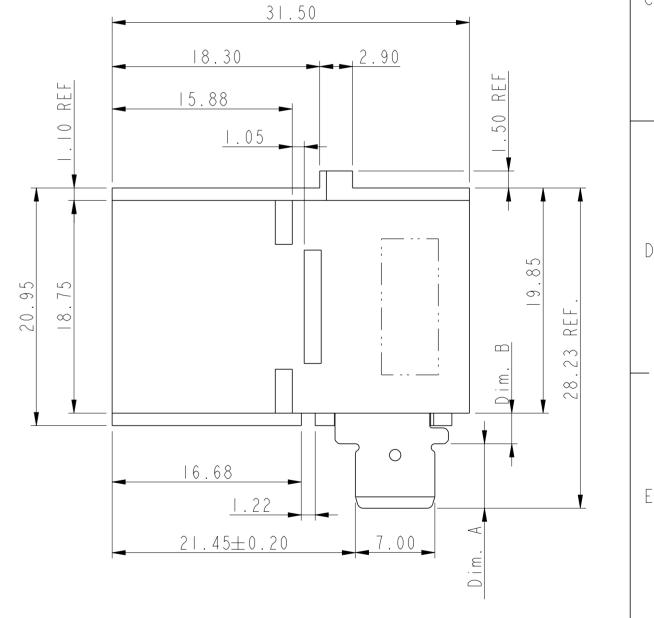
5	6	7	8





В





spec ref	-			dr	Zhao Peter	2	013/06/20	project	ion	ΝΛ	М	size	scale	
tolerance std					Jackbin Zou	2	017/06/22	Φr	\neg	V		A 2	3:1	
ISO 406	I TOLEH I OTHERW	TOLERANCES UNLESS THERWISE SPECIFIED		chr	-	-		·		-		ecn no	ELX-DG-27194-1	
ISO 0	OTHERWISE STECTIED		appr	Pei-Ming Zheng	2	017/06/28	product fo	amily			rel level	Released		
		0.X	±0.30	Amphon	ohenol – Solder Tab			0 L					rev	
surface - /	linear	0.XX	±0.25	Am		_					D D	10125600		
		0.XXX	±0.10			⊢ Bark	lip R/A CON	NECTOR			dwg			D
ISO I30Ž	angular	0°	±2°	www.	fci.com	cat. no.		-	Pro	duct –	Customer	Drw	sheet I of	I
5			PDS	6: Re	v :D		ST	ATUS:Rel	leased		Pri	nted: Jun	28, 2017	